

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	0	(strain and reliability and determining and evaluating and predict).clm.	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/09/01 10:57

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	56	(strain with bottom near5 (via hole trench groove)) and (chip die 'ic')	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/09/01 10:45
L2	60	(strain with bottom near5 (via hole trench groove)) and (semiconductor)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/09/01 10:47
L3	171	(evaluat\$4 near4 reliability) with (chip die 'ic')	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/09/01 10:49
L4	8	3 and (liner barrier seed) with (trench via groove hole via)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/09/01 10:50
L5	8	3 and (liner barrier seed) with (trench via groove hole via)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/09/01 10:50